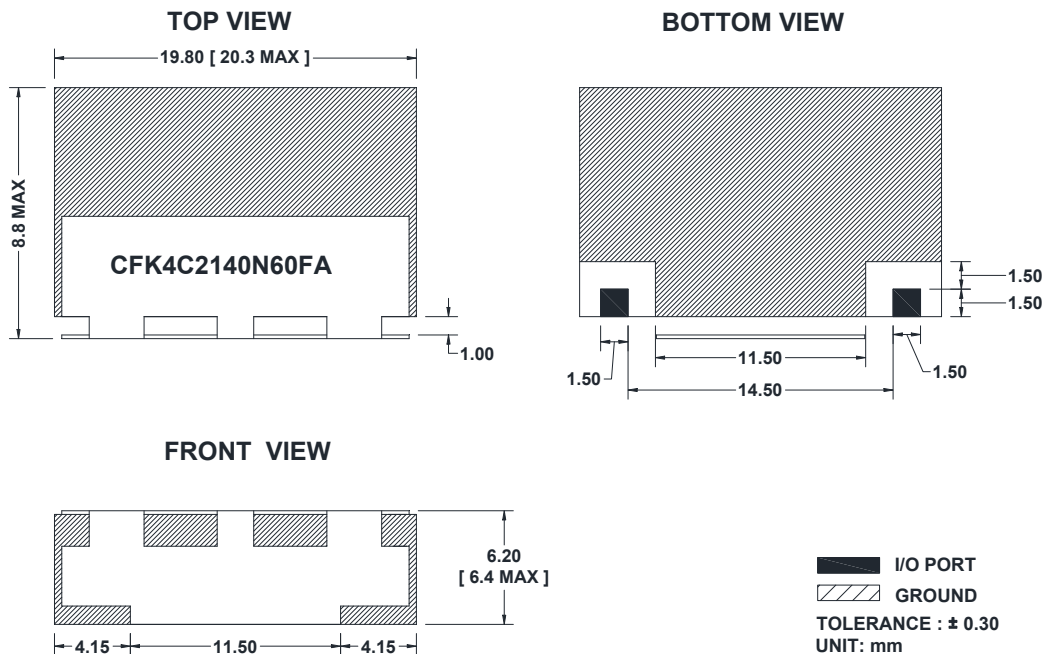


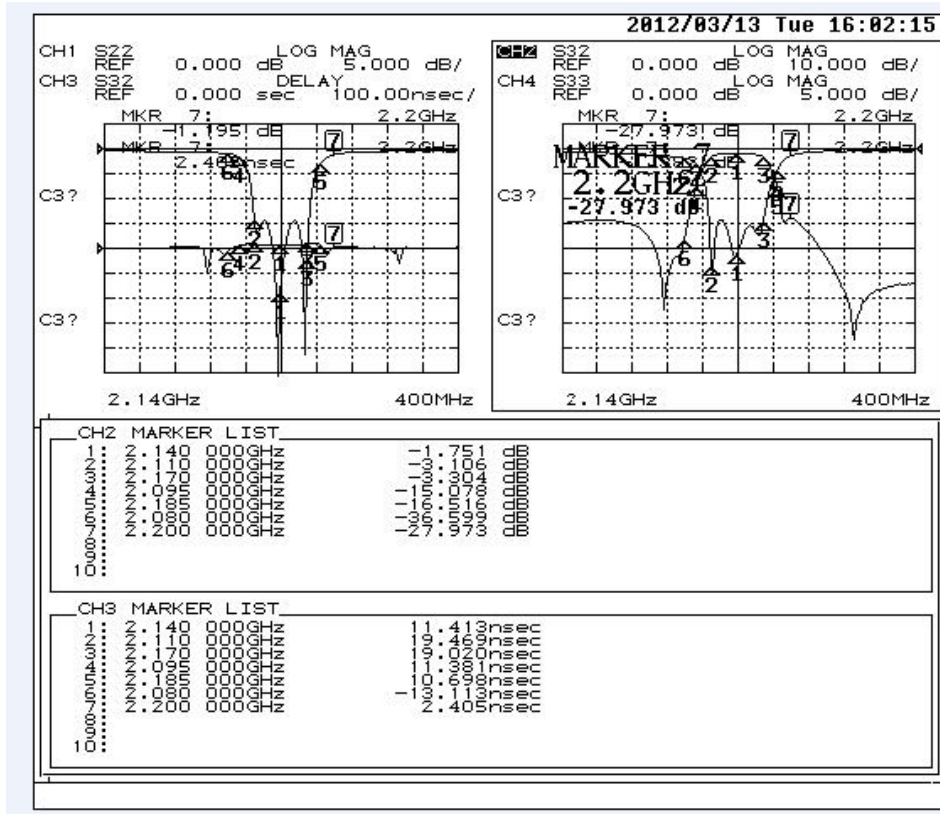
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	2140	MHz
Bandwidth [BW]	fo ±30 [2110 ~ 2170]	MHz
Insertion Loss in BW	3.5	dB max
Ripple in BW	2.0	dB max
Return Loss in BW	14	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	10dBc min @ fo ± [2095]	MHz
	5dBc min @ fo ± [2185]	MHz
	30.0dBc min @ fo ± [2080 ~]	MHz
	20.0dBc min @ fo ± [2200 ~]	MHz
Group Delay Variation	150	ns max
Input Power	1	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

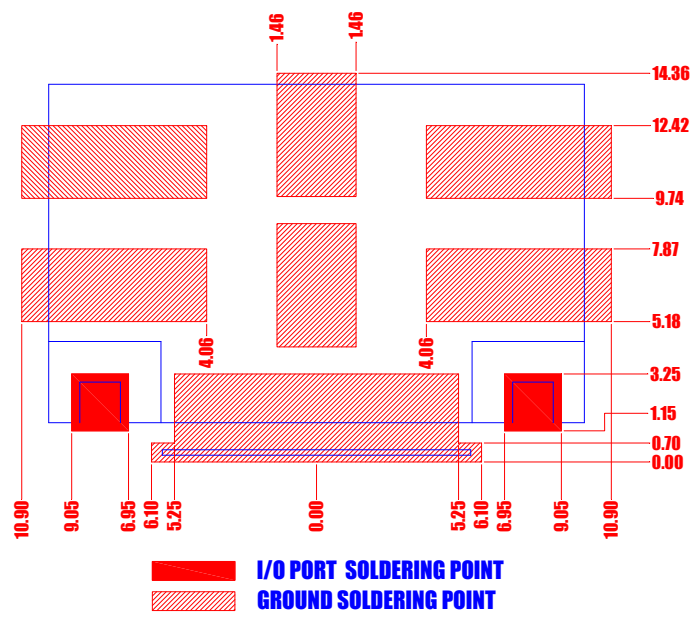
Mechanical Specification



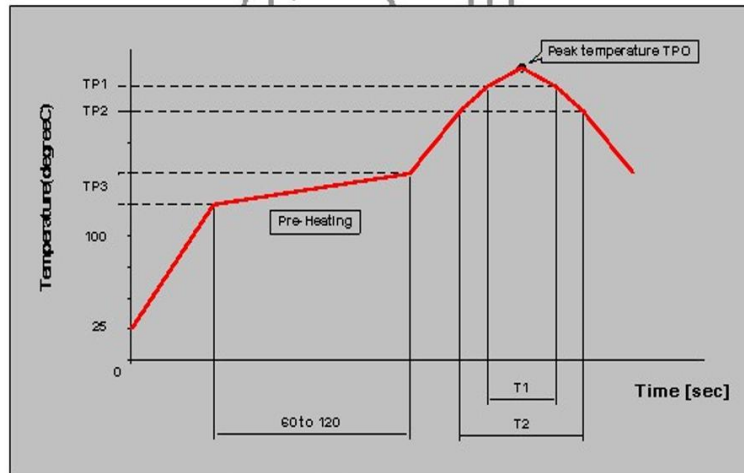
Plot Data



Recommended PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/0	240	20	220	70	150 to 180